

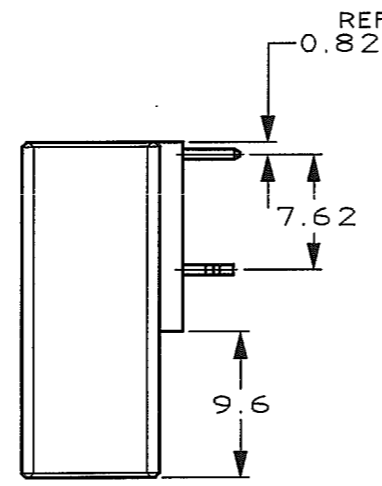
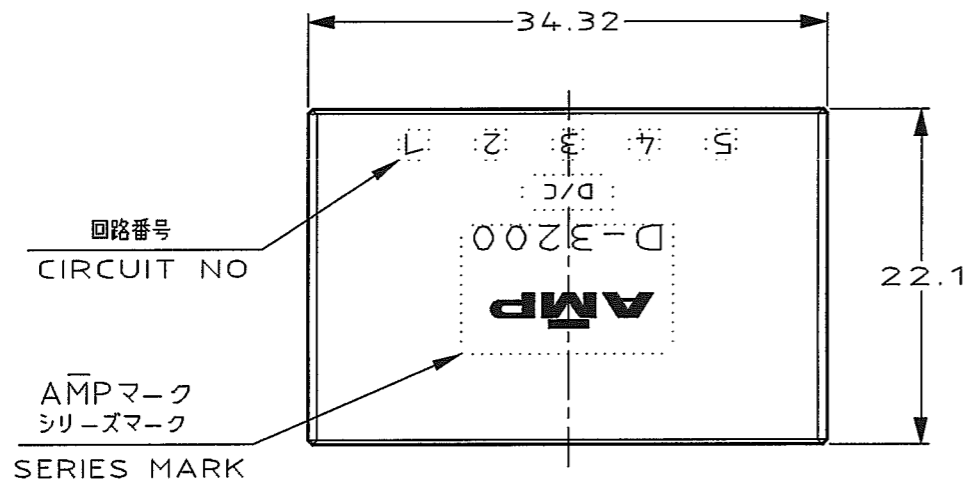
NUMBER
316130

3rd ANGLE PROJECTION

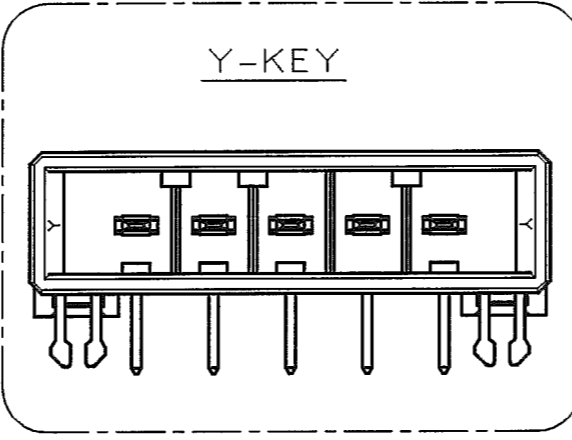
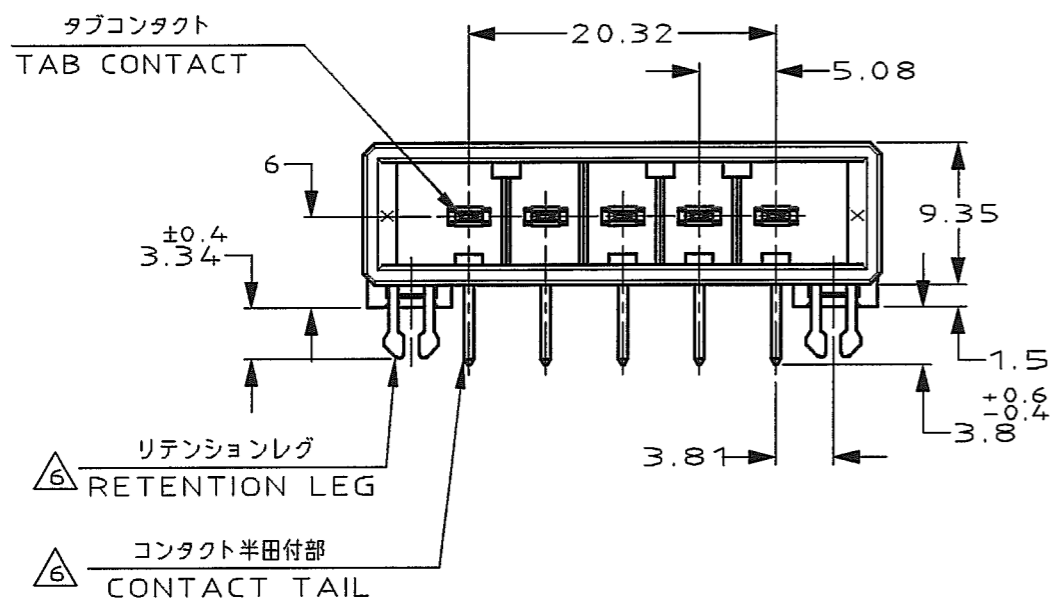
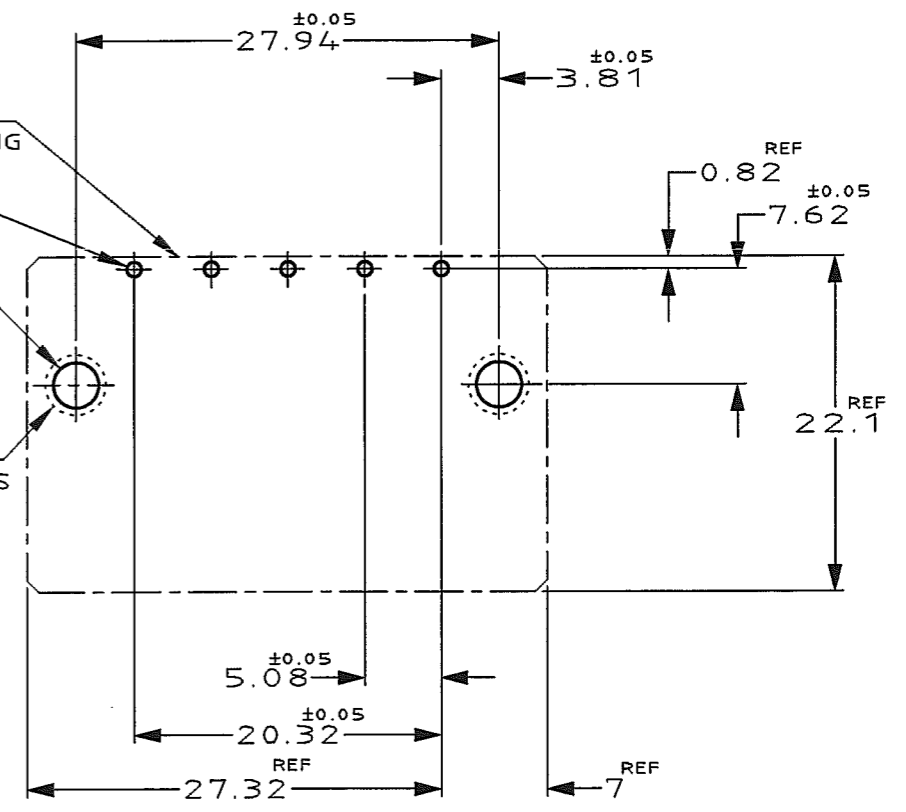
METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



- コネクタ外形
OUTLINE OF HEADER HOUSING
- 5-φ1.1 ±0.1
DIA 1.1±0.1 5 PLACES
- スルーホール 2-φ3 ±0.1
DIA 3±0.1 2 PLACES
- ラウンド 2-φ4MIN
ROUND DIA 4MIN 2 PLACES



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38μm PdNi & Au PLATING OVER NICKEL OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76μm PdNi & Au PLATING OVER NICKEL OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN LEAD PLATED
(CONTACT TAIL) OVER NICKEL
 - FINISH (RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL
 - OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

△6	△4	2-316130-5	Y	OBSOLETE
△6	△3	2-316130-3	Y	
△6	△2	2-316130-2	Y	
△6	△4	1-316130-5	X	
△6	△3	1-316130-3	X	
△6	△2	1-316130-2	X	
(FINISH)		製品番号 (PART NO.)	KEY	

C	REVISED PER ECR-25-250788	F.Z	R.B	16 JAN 2025
B1	ECO-10-000445	KK	AEG	JAN10
B	REVISED (FJD0-0039-03)	TS	SM	25 APR '03
A	REVISED (FJD0-0114-03)	TS	SM	25 APR '03
0	RELEASED (FJ00-2557-95)	KI	YI	31 JUL '93
LTR	REVISION RECORD	DR	CHK	DATE

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WIRE RANGE mm (AWG -)	INSULATION DIA mmφ
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. 26/JUL/95 K.IKEDA	DE. 26/JUL/95 K.IKEDA
CHK. 31 JUL 95 Y.ISHIKAWA	APP. 31 JUL 95 S.MANABE

NAME 5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200			
一般公差 (GENERAL TOLERANCE)	SIZE A3	LOC J	NUMBER C= 316130
100% : ±0.2 100% 300% : ±0.3 300% 1000% : ±0.4 角 度 : ±3'	SCALE 2-1	REV. C	SHEET 1 OF 1